

Xytron™ TC6022I

PPS-(GF+MX)60

Thermal conductive material

Properties	Typical Data	Unit	Test Method
Rheological properties			
	Value		
Molding shrinkage (parallel)	0.2	%	ISO 294-4
Molding shrinkage (normal)	0.5	%	ISO 294-4
Mechanical properties			
	Value		
Tensile modulus	22000	MPa	ISO 527-1/-2
Tensile modulus (120°C)	12200	MPa	ISO 527-1/-2
Tensile modulus (160°C)	9900	MPa	ISO 527-1/-2
Tensile modulus (180°C)	9150	MPa	ISO 527-1/-2
Stress at break	120	MPa	ISO 527-1/-2
Stress at break (120°C)	78.5	MPa	ISO 527-1/-2
Stress at break (160°C)	63	MPa	ISO 527-1/-2
Stress at break (180°C)	55	MPa	ISO 527-1/-2
Strain at break	0.7	%	ISO 527-1/-2
Strain at break (120°C)	1.2	%	ISO 527-1/-2
Strain at break (160°C)	1.5	%	ISO 527-1/-2
Strain at break (180°C)	1.3	%	ISO 527-1/-2
Flexural modulus	23200	MPa	ISO 178
Flexural strength	215	MPa	ISO 178
Flexural modulus (120°C)	13800	MPa	ISO 178
Flexural modulus (160°C)	11000	MPa	ISO 178
Flexural modulus (180°C)	10100	MPa	ISO 178
Charpy impact strength (+23°C)	16	kJ/m ²	ISO 179/1eU
Charpy impact strength (-30°C)	16	kJ/m ²	ISO 179/1eU



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Properties	Typical Data	Unit	Test Method
Charpy notched impact strength (+23°C)	9	kJ/m ²	ISO 179/1eA
Charpy notched impact strength (-30°C)	9	kJ/m ²	ISO 179/1eA
Rockwell hardness, R scale	120	-	ISO 2039-2
Rockwell hardness, M scale	100	-	ISO 2039-2

Thermal properties

Value

Melting temperature (10°C/min)	280	°C	ISO 11357-1/-3
Temp. of deflection under load (1.80 MPa)	265	°C	ISO 75-1/-2
Coeff. of linear therm. expansion (parallel)	0.11	E-4/°C	ISO 11359-1/-2
Coeff. of linear therm. expansion (normal)	0.3	E-4/°C	ISO 11359-1/-2
Coef. of lin. therm expansion, parallel, above Tg	0.12	E-4/°C	ISO 11359-1/-2
Coef. of lin. therm expansion, normal, above Tg	0.72	E-4/°C	ISO 11359-1/-2
Burning Behav. at 3.0 mm nom. thickn.	V-0	class	IEC 60695-11-10
Thickness tested	3	mm	IEC 60695-11-10
UL recognition	Yes	-	-
Relative Temperature Index - electrical	130	°C	UL746B
RTI electrical (Thickness (1) tested)	0.4	mm	UL746B
Thermal conductivity in plane	2.2	W/(m K)	ASTM E1461
Thermal conductivity through plane	1.2	W/(m K)	ASTM E1461

Electrical properties

Value

Volume resistivity	>1E13	Ohm*m	IEC 62631-3-1
Comparative tracking index	225	V	IEC 60112

Other properties

Value

Density	1850	kg/m ³	ISO 1183
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